

ABSTRACT OF DISCLOSURE

A cavity-down ball grid includes a flexible circuit tape including a flexible tape laminated to a conductor layer. The flexible circuit tape has an aperture therein. A thermally conductive heat spreader is fixed to a first surface of the flexible circuit tape and the heat spreader has a cavity aligned with the aperture of the flexible circuit tape. A semiconductor die is mounted to the heat spreader in a die-down configuration in the cavity. A thermally conductive die adapter is fixed to the semiconductor die such that a portion of the die adapter protrudes from the cavity. A plurality of wire bonds connect the semiconductor die to bond sites on the second surface of the flexible circuit tape. An encapsulating material encapsulates the semiconductor die and the wire bonds and a plurality of solder balls are disposed on a second surface of the flexible circuit tape, in the form of a ball grid array.